

# EMI Ferrite Bead



## BBUP Series



### Overview

EMI ferrite beads are made of ferrite material, which can block high-frequency noise while allowing required signals to pass through, providing high impedance and noise attenuation to improve signal integrity/efficiency and reduce power loss.

### Benefits

1. For Power Line
2. Compliance with EMI regulations.
3. Reduced power loss and improved system efficiency
4. Operating temperature range: -55 ~ +125°C
5. Improved signal integrity

### Applications

1. Wearable device
2. Industrial
3. Communications
4. Consumer Electronics

### Product Information

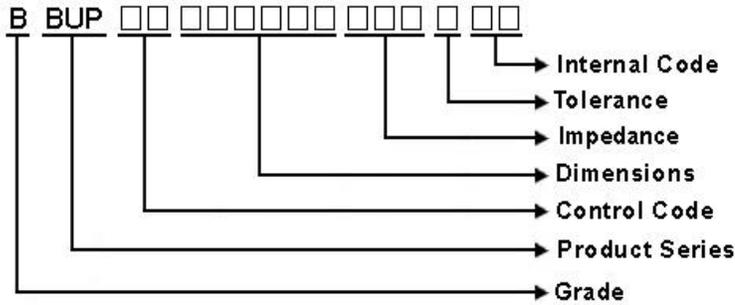
Series	Size Code (JIS/EIA)	Impedance ( $\Omega$ )
BBUP	1005/0402 1608/0603 2012/0805 3216/1206 4532/1812	10 ~ 470



## BBUP00201209 Series Specification

**1** **Scope:** This specification applies to MULTILAYER FERRITE CHIP BEADS

**2** **Part Numbering:**



**3** **Rating:**

Operating Temperature: - 5 5 °C ~ 1 2 5 °C(Including self - temperature rise)

Storage Temperature: - 5 5 °C ~ 1 2 5 °C(after PCB)

- 5 °C~ 4 0 °C, Humidity 4 0 %~ 7 0 %(before PCB)

**4** **Marking:**

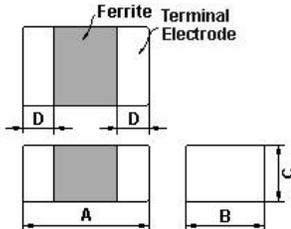
No Marking

**5** **Standard Testing Condition**

	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35°C)	20 to 30°C
Humidity	Ordinary Humidity(25 to 85% RH)	50 to 80 %RH

## BBUP00201209 Series Specification

### 6 Configuration and Dimensions:



Dimensions in mm	
TYPE	201209
A	2.00±0.20
B	1.25±0.20
C	0.90±0.20
D	0.50±0.30

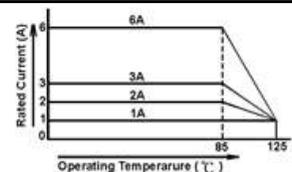
Net Weight (grms)	
Size Code	Net Weight (grms)
201209	0.01231

### 7 Electrical Characteristics:

Part No.	Impedance (Ω)	Test Freq.	RDC (Ω)Max.	Rated Current (mA)Max.
BBUP00201209150□00	15	100 MHz,200 mV	0.012	6000
BBUP00201209220□00	22	100 MHz,200 mV	0.012	6000
BBUP00201209300□00	30	100 MHz,200 mV	0.012	6000
BBUP00201209310□00	31	100 MHz,200 mV	0.012	6000
BBUP00201209500□00	50	100 MHz,200 mV	0.015	6000
BBUP00201209600□00	60	100 MHz,200 mV	0.018	6000
BBUP00201209800□00	80	100 MHz,200 mV	0.02	6000
BBUP00201209101□00	100	100 MHz,200 mV	0.02	5000
BBUP00201209121□00	120	100 MHz,200 mV	0.02	5000
BBUP00201209201□00	200	100 MHz,200 mV	0.04	3000
BBUP00201209221□00	220	100 MHz,200 mV	0.04	3000
BBUP00201209301□00	300	100 MHz,200 mV	0.05	3000
BBUP00201209331□00	330	100 MHz,200 mV	0.05	3000

**NOTE:** □-tolerance Y=±25% / T=±30%

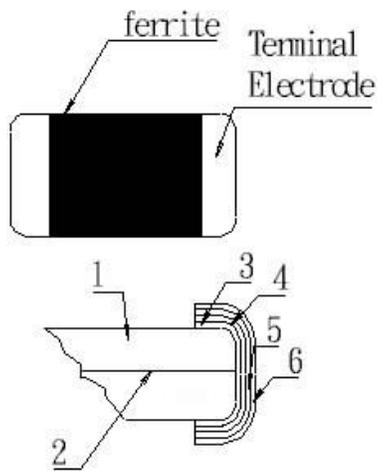
1. Operating temperature range - 5 5°C ~ 1 2 5°C(Including self - temperature rise)
2. Rate Current : Applied the current to coils, the temperature rise shall not be more than 30°C
3. As for BBUP type. Rated Current is derated as right figure depending on the operating temperature.



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### 8 BBUP00201209 Series

#### 8.1 Construction:



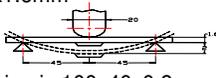
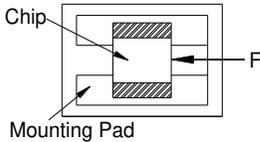
#### 8.2 Material List:

No	Part	Material
1	Ferrite Substance	NiO-CuO-ZnO-Ferrite
2	Silver electrode	Ag
3	Silver electrode	Ag
4	Cu plating	Cu
5	Ni plating	Ni
6	Sn plating	Sn

## BBUP00201209 Series Specification

### 9 Reliability Of Ferrite Multilayer Chip Bead

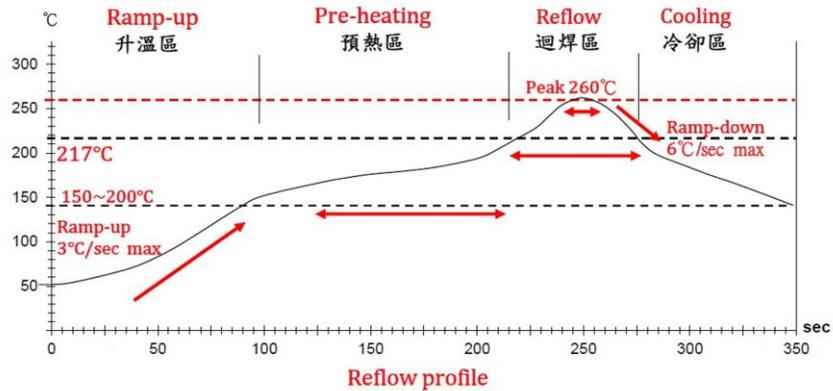
#### 1-1.Mechanical Performance

No	Item	Specification	Test Method
1-1-1	Flexure Strength	The forces applied on the right conditions must not damage the terminal electrode and the ferrite	Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6mm Deflection: 2.0mm Keeping Time: 30sec *For 100505, substrate dimension is 100x40x0.8mm 
1-1-2	Vibration		Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1min Amplitude: 1.5mm Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage More than 75% of the terminal electrode should be covered with solder. Impedance : within $\pm 30\%$ of initial value	Pre-heating: 150°C, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 260 $\pm 5$ °C Immersion Time: 10 $\pm 1$ sec
1-1-4	Solder ability	The electrodes shall be at least 95% covered with new solder coating	Pre-heating: 150°C, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 245 $\pm 5$ °C (Pb-Free) Immersion Time: 4 $\pm 1$ sec
1-1-5	Terminal Strength Test	No split termination  Chip Mounting Pad	Test device shall be soldered on the substrate, then apply a force in the direction of the arrow. Force : 5N Keeping Time: 10 $\pm 1$ sec

#### 1-2.Environmental Performance

No	Item	Specification	Test Method															
1-2-1	Temperature Cycle	Appearance: No damage Impedance: within $\pm 30\%$ of initial value	One cycle: <table border="1"> <thead> <tr> <th>Step</th> <th>Temperature (°C)</th> <th>Time (min)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-55<math>\pm 3</math></td> <td>30</td> </tr> <tr> <td>2</td> <td>25<math>\pm 2</math></td> <td>3</td> </tr> <tr> <td>3</td> <td>125<math>\pm 3</math></td> <td>30</td> </tr> <tr> <td>4</td> <td>25<math>\pm 2</math></td> <td>3</td> </tr> </tbody> </table> Total: 100cycles Measured after exposure in the room condition for 24hrs	Step	Temperature (°C)	Time (min)	1	-55 $\pm 3$	30	2	25 $\pm 2$	3	3	125 $\pm 3$	30	4	25 $\pm 2$	3
Step	Temperature (°C)	Time (min)																
1	-55 $\pm 3$	30																
2	25 $\pm 2$	3																
3	125 $\pm 3$	30																
4	25 $\pm 2$	3																
1-2-2	Humidity Resistance		Temperature: 40 $\pm 2$ °C Relative Humidity: 90 ~ 95% / Time: 1000hrs Measured after exposure in the room condition for 24hrs															
1-2-3	High Temperature Resistance		Temperature: 125 $\pm 3$ °C / Relative Humidity: 0% Applied Current: Rated Current /Time: 1000hrs Measured after exposure in the room condition for 24hrs															
1-2-4	Low Temperature Resistance		Temperature: -55 $\pm 3$ °C Relative Humidity: 0% / Time: 1000hrs Measured after exposure in the room condition for 24hrs															

## BBUP00201209 Series Specification



Lead-Free(LF)標準溫度分析範圍

Refer to J-STD-020C

管制項目 Item.	升温區 Ramp-up	預熱區 Pre-heating	迴焊區 Reflow	Peak Temp	冷卻區 Cooling
溫度範圍 Temp.scope	R.T ~ 150°C	150°C ~ 200°C	Above 217°C	260±5°C	Peak Temp.~150°C
標準時間 Time spec.	-	60 ~ 180 sec	60 ~ 150 sec	20 ~ 40 sec	-
實際時間 Time result	-	75 ~ 100 sec	90 ~ 120 sec	20 ~ 35 sec	-

NOTE :

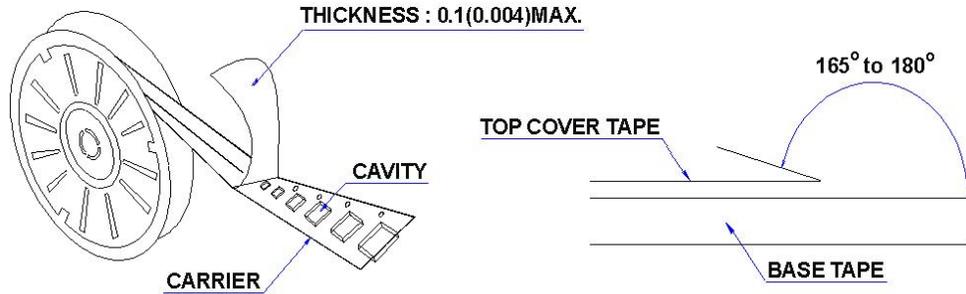
1. Re-flow possible times : within 2 times
2. Nitrogen adopted is recommended while in re-flow
3. Products can only be soldered with reflow

## BBUP00201209 Series Specification

### 11 Packaging:

#### 11.1 Packaging -Cover Tape

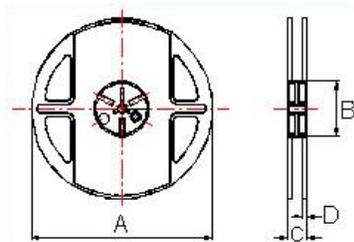
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



#### 11.2 Packaging Quantity

TYPE	PCS/REEL
100505	10000
160805	10000
160808	4000
201209	4000

#### 11.3 Reel Dimensions



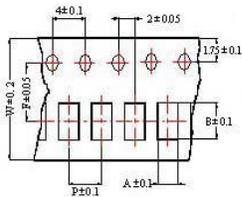
Dimensions in mm

TYPE	A	B	C	D
100505	178	60	12	1.5
160805	178	60	12	1.5
160808	178	60	12	1.5
201209	178	60	12	1.5

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### 11 Packaging:

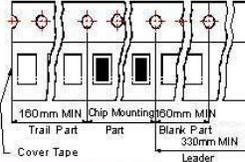
#### 11.4 Tape Dimensions in mm



#### Tape Material

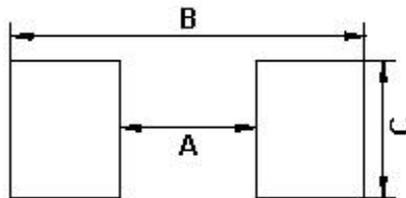
Carrier tape : Paper

Cover tape : Polyethylene



TYPE	A	B	T	W	P	F
100505	0.62	1.12	0.60	8	2	3.5
160805	1.05	1.85	0.60	8	2	3.5
160808	1.05	1.85	0.95	8	4	3.5
201209	1.50	2.30	0.97	8	4	3.5

### 12 Recommended Land Pattern:



Dimensions in mm

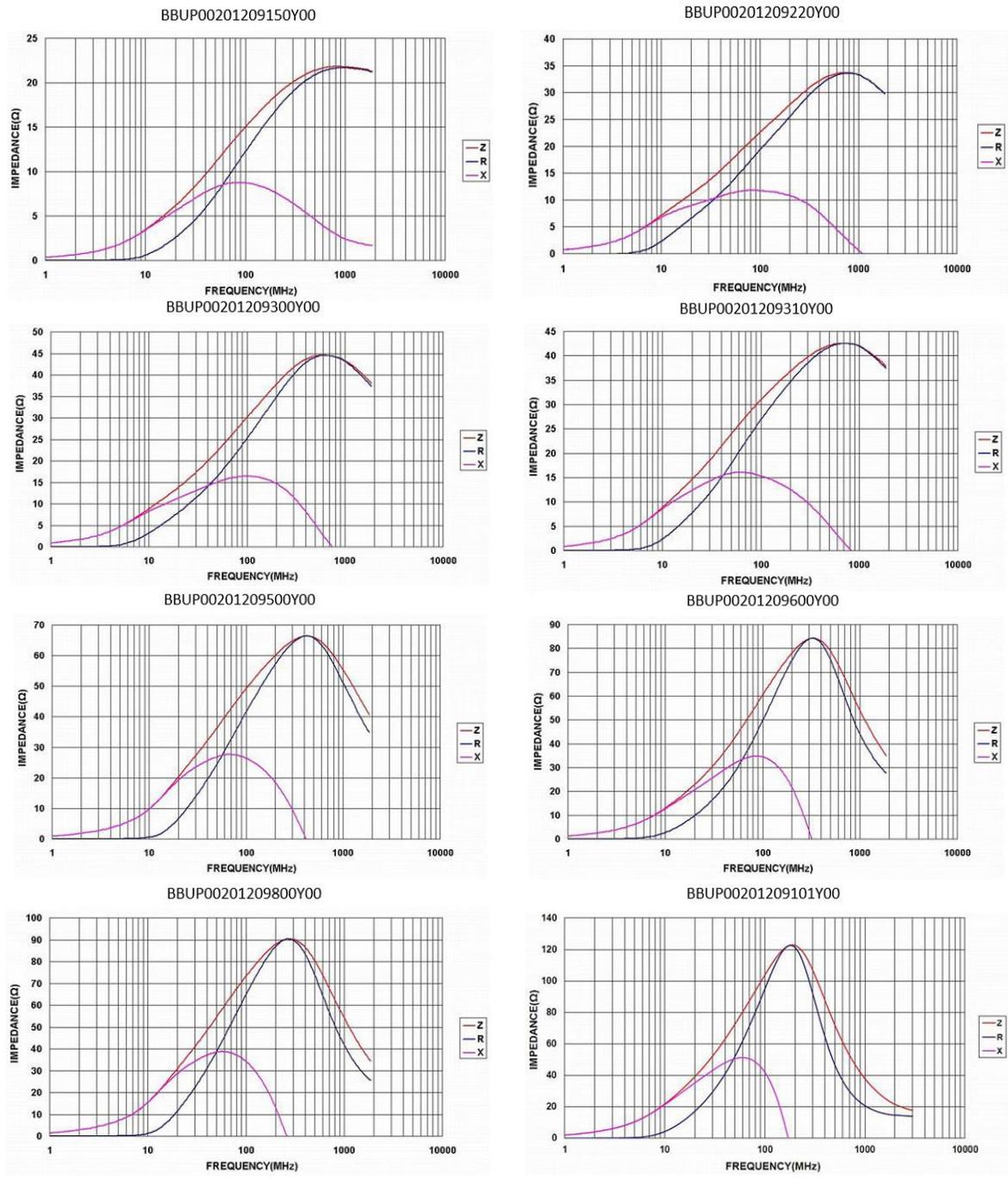
TYPE	A	B	C
201209	1.0 ~ 1.2	2.6 ~ 4.0	1.0 ~ 1.4

### 13 Note:

1. Please make sure that your product has been evaluated and confirmed against your specifications when our product is mounted to your product.
2. Do not knock nor drop.
3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose, under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
4. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)
5. The moisture sensitivity level (MSL) of products is classified as level 1.

# BBUP00201209 Series Specification

**14** Graph:



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